

# **Micro- & Nano-Technologies Enabling More Compact, Lightweight Thermoelectric Power Generation & Cooling Systems**

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**Energy & Efficiency Division**

**MicroProducts Breakthrough Institute**

**Corvallis, OR**

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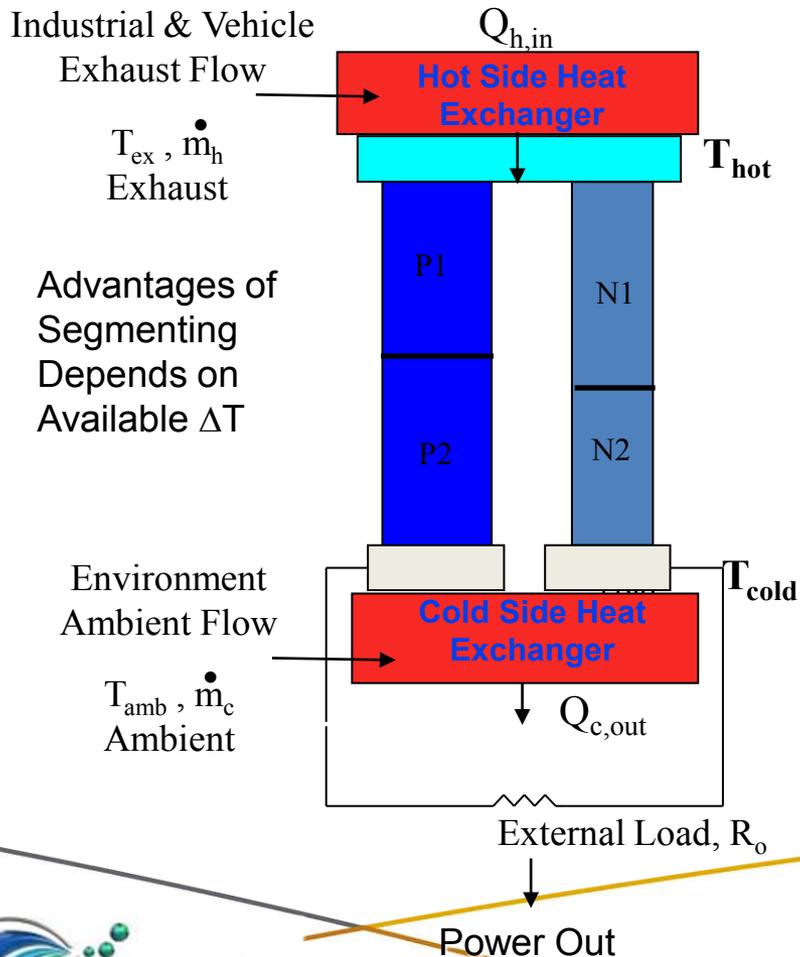


*Proudly Operated by Battelle Since 1965*

# Advanced Thermoelectric System Design

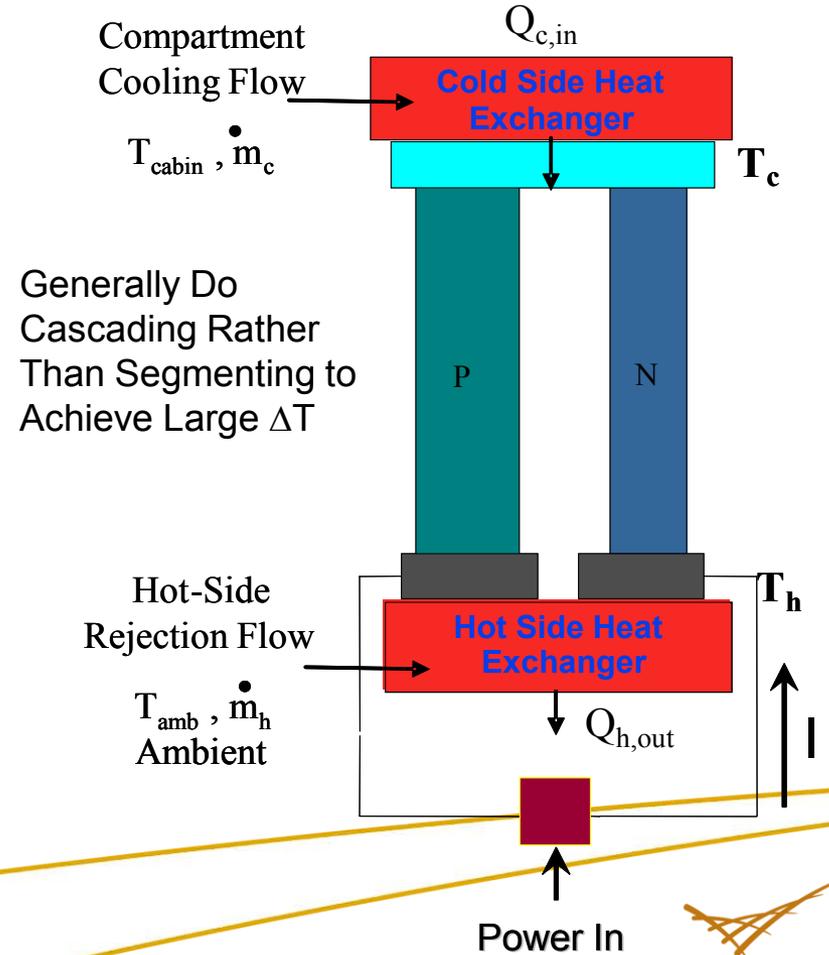
## Single & Segmented Material TE Legs

### Thermoelectric Power Generation High-Temperature Systems



Advantages of Segmenting Depends on Available  $\Delta T$

### Thermoelectric Heating/Cooling Low-Temperature Systems



Generally Do Cascading Rather Than Segmenting to Achieve Large  $\Delta T$

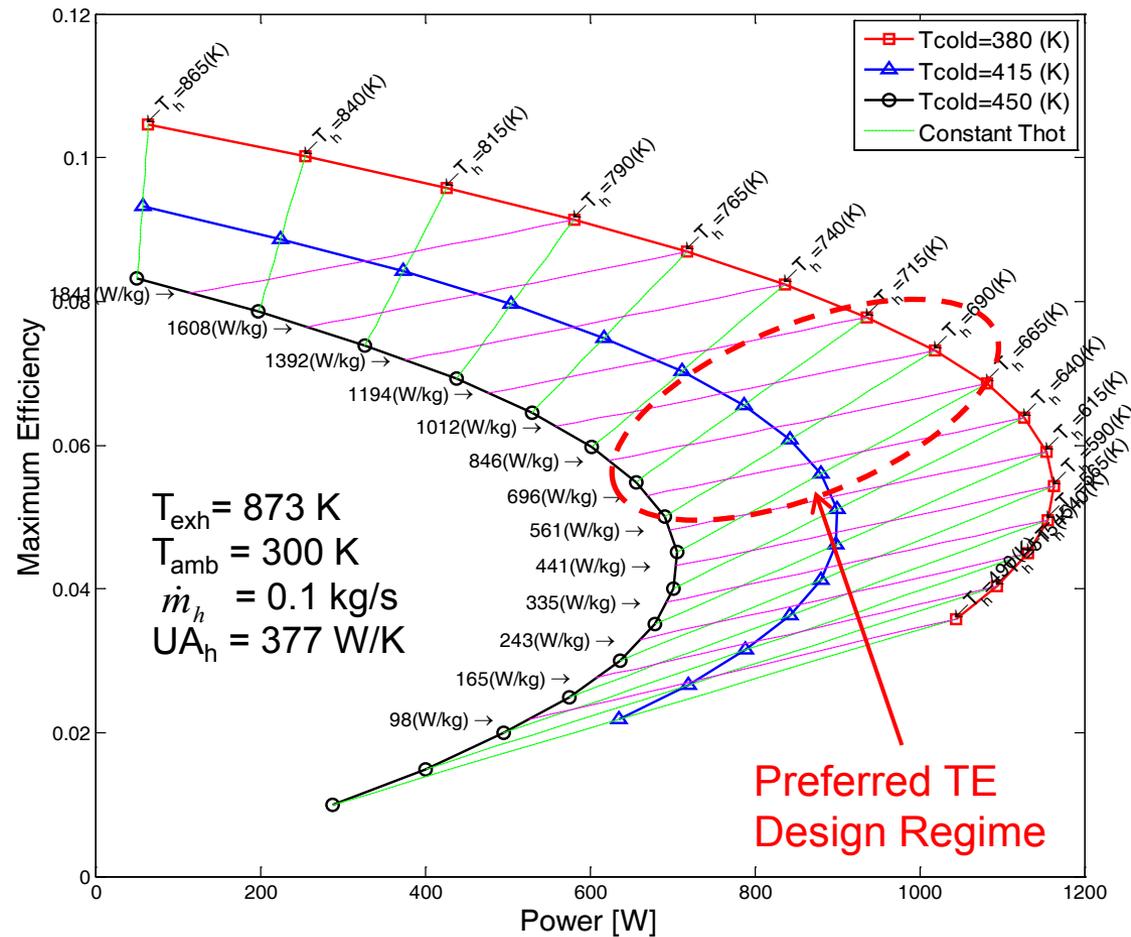


# TE Power Generation

## Heat Exchanger / TE Device Integration Requirements

- Regions of Higher Specific Power Also Associated with Higher Heat Flux Regions
- Hot Side Heat Exchanger Dictates:
  - TE Specific Power
  - TE Power Flux
  - TE Volumetric Specific Power
- Heat Fluxes  $> 15 \text{ W/cm}^2$  in Preferred Design Regimes
  - Hot-side
  - Cold-side

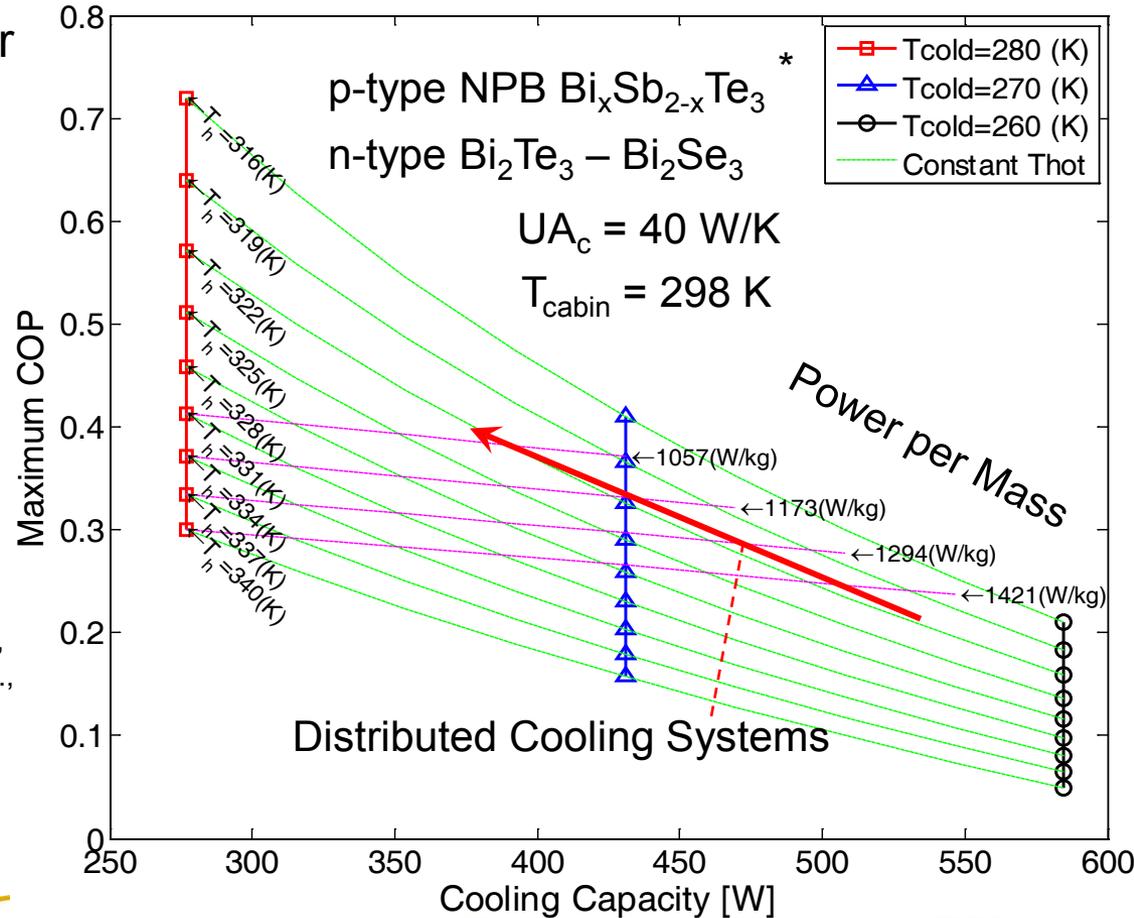
Segmented Skutterudite  
/Bi<sub>2</sub>Te<sub>3</sub> Materials



# TE Cooling

## Heat Exchanger / TE Device Integration Requirements

- Typical COP – Cooling Capacity – Power / Mass Relationship Shown
- Distributed TE Cooling Systems
  - Create Lower Heat Flows per Unit
  - Higher COP's
  - Lower Power / Mass
- Generally Right Directions for Automotive Distributed Cooling

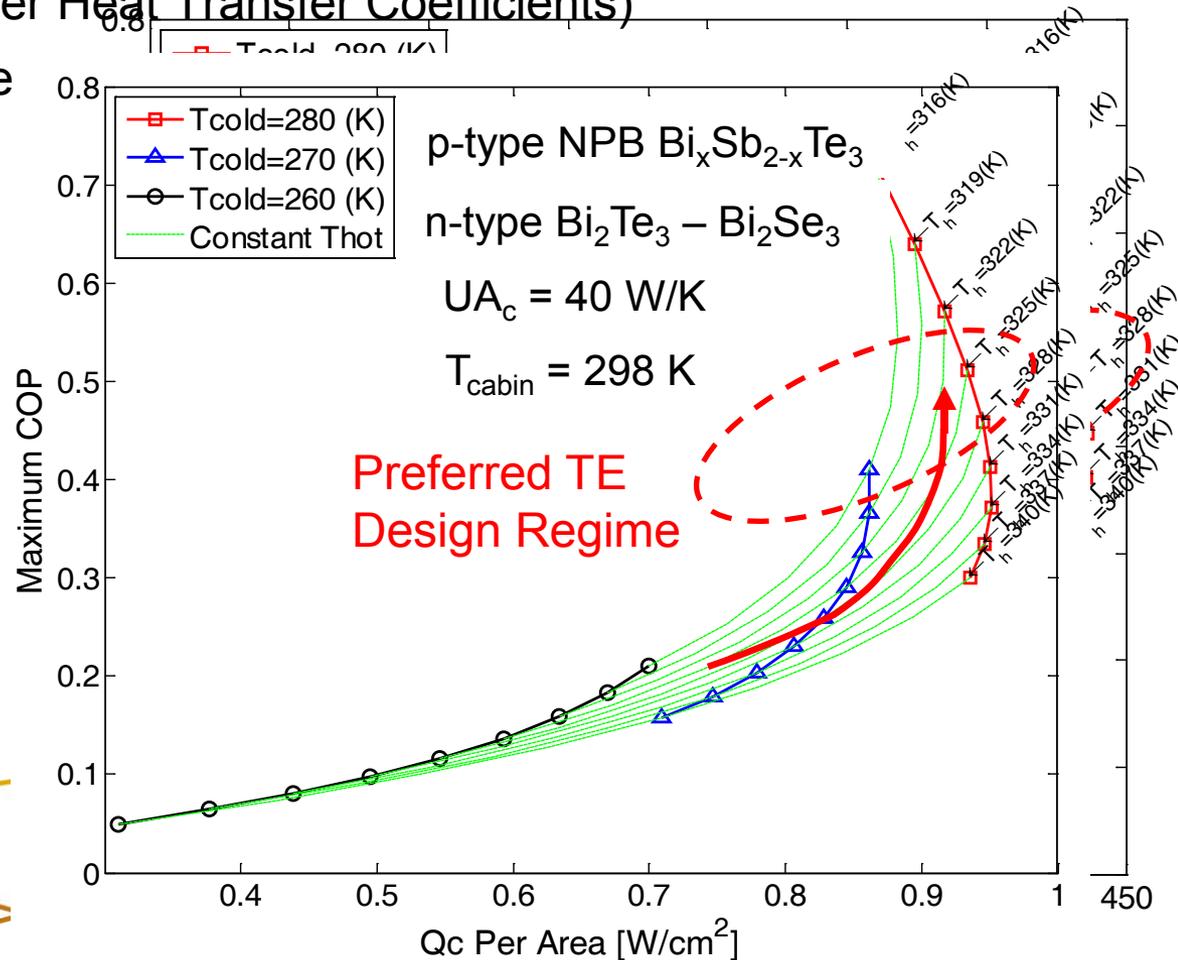


\* Poudel, B., Hao, Q.H., Ma, Y., Lan, Y., Minnich, A. Yu, B., Yan, X., Wang, D., Muto, A., Vashaee, D., Chen, X., Liu, J., Dresselhaus, M.S., Chen, G., Ren, Z., 2008, "High-Thermoelectric Performance of Nanostructured Bismuth Antimony Telluride Bulk Alloys," *Scienceexpress*, 10.1126, science.1156446.

# TE Cooling

## Heat Exchanger / TE Device Integration Requirements

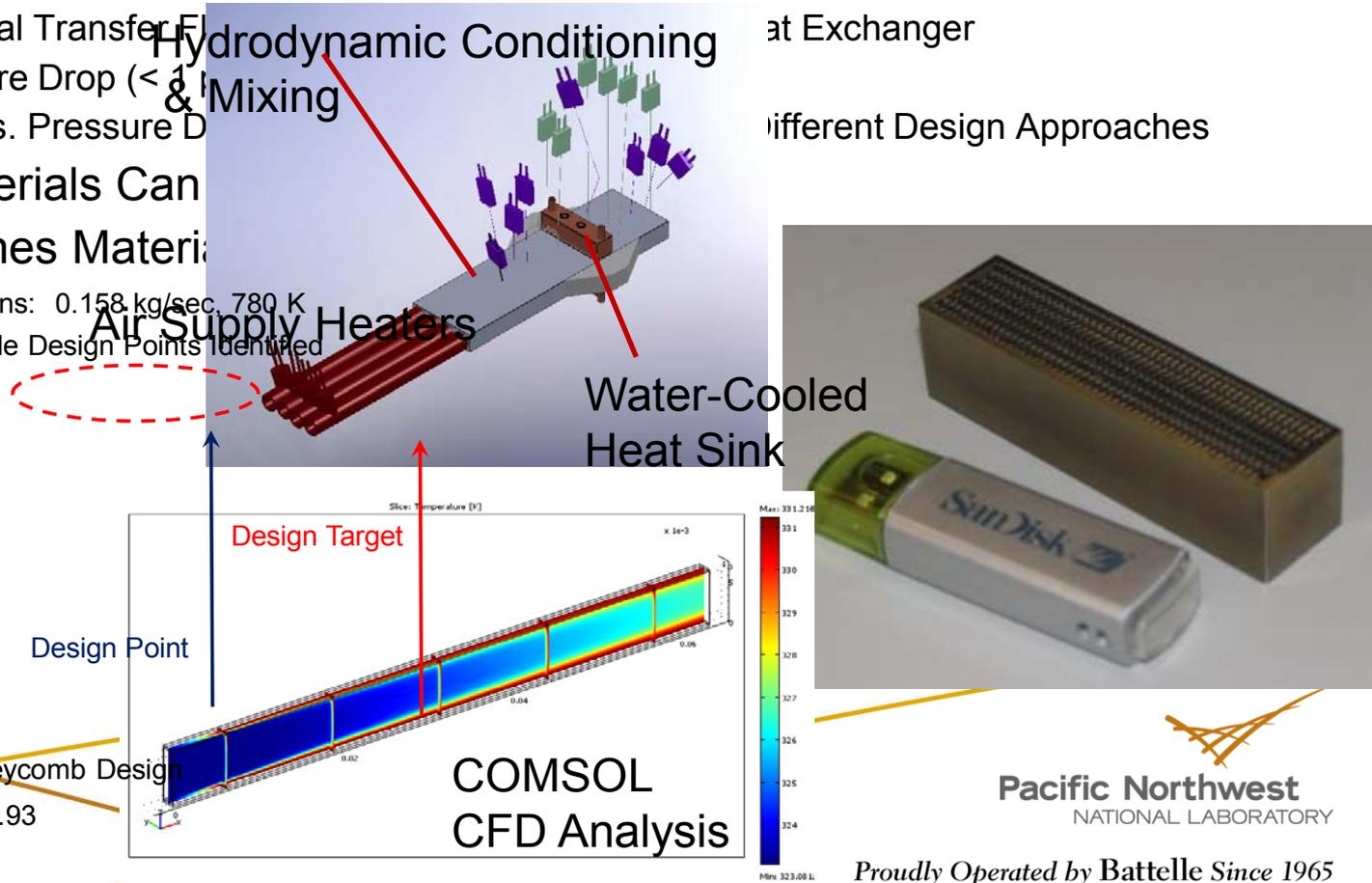
- Distributed TE Cooling Systems Generally Move Into Regions of:
  - Higher COP's
  - Higher Specific Cooling Capacity (Compact, Lightweight Systems)
  - Higher Heat Fluxes (Higher Heat Transfer Coefficients)
- Generally Higher Performance Heat Exchanger Systems Required



# PNNL Developing High-Performance Microtechnology Heat Transfer Technologies

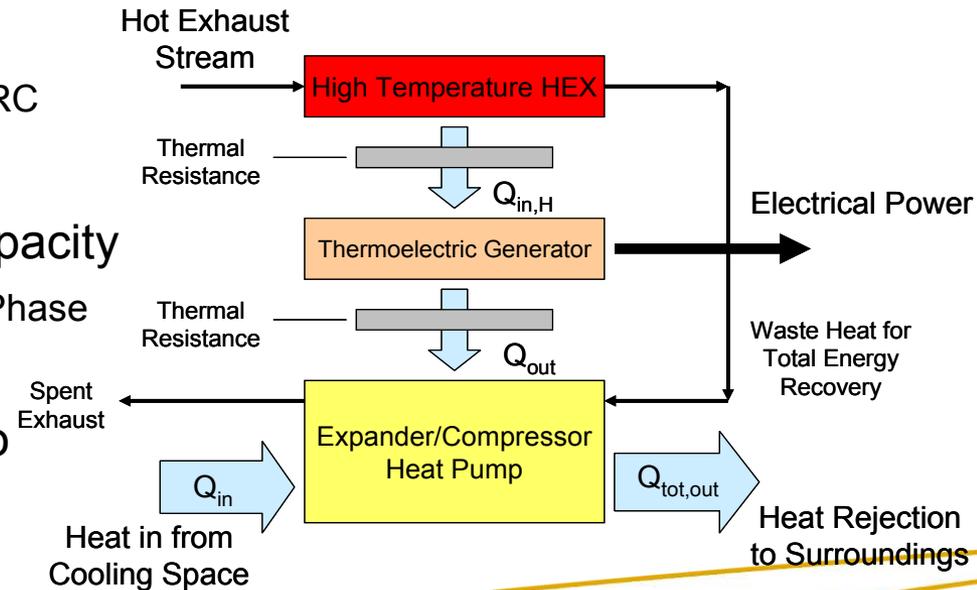
- TE Power Generation From TQG Exhaust Energy Recovery
  - Hot-Side Heat Exchanger Designs Being Developed & Refined
  - CFD Analyses & Experimental Testing Helping to Refine Designs
  - Design Performance Goals:
    - High Thermal Transfer Efficiency at Exchanger
    - Low Pressure Drop ( $< 1$  bar) at Exchanger
    - Heat Flux vs. Pressure Drop at Exchanger
  - Different Materials Can Be Used: Inconel, Haynes Materials

60 kW TQG Design Conditions: 0.158 kg/sec, 780 K  
 Several Workable Design Points Identified



# Co-Functional Power / Cooling Systems

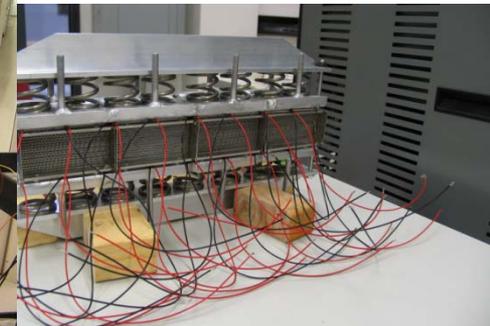
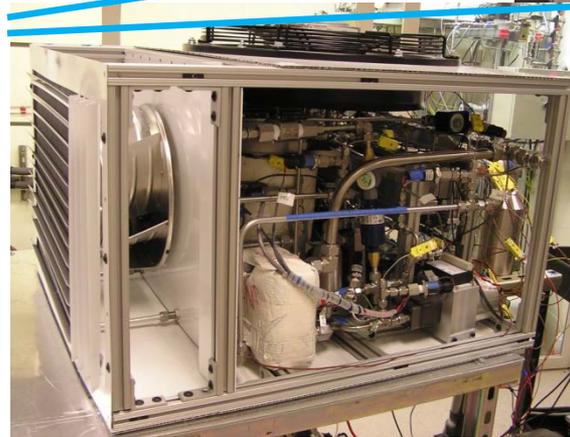
- Co-Functional Integration of 3 Power & Cooling Technologies
  - Organic Rankine Cycle Based Cooling
  - Thermoelectric Power Generation
  - Micro/Nano Heat Transfer Technologies (Microchannel Heat Exchangers)
- System Designed, Fabricated & Tested at PNNL MBI
- TE Topping Cycle
  - Step-Down (Lower) Input Temperatures to ORC
  - Simultaneously Produce Useful Power
- E/C ORC to Provide Useful Cooling Capacity
  - Known & Demonstrated Components in this Phase
  - Reduce Cost & Risk & Development Time
- Microchannel Heat Exchangers Used to Dramatically Reduce Volume & Weight
- Funded by U.S. Army RDECOM



# CFPC – Fabrication & Test

- First-in-Class, Pioneering System
- TEG Power System Uses MicroChannel Heat Exchangers
  - Stainless Steel Air HX On Hot-Side
  - Aluminum R245fa HX on Cold-Side
- High-Temperature  $\text{Bi}_2\text{Te}_3$  Modules
  - First-Ever  $320^\circ\text{C}$   $\text{Bi}_2\text{Te}_3$  Modules
- System Size
  - Dimensions: 30" X 30" X 19"
  - Weight: ~100 kgs
- System Fabrication Completed
- System Testing Completed
  - Exhaust Heat Simulated with Electrical Heater / Blower System
  - Stable System Operation
  - Many Performance Metrics Satisfied

TEG Power System



Co-Functional System Build-up

ORC Boiler

Scroll Expander



Pacific Northwest  
NATIONAL LABORATORY

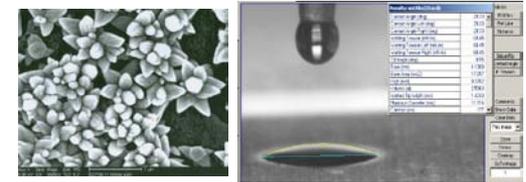
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# MicroTechnology in Distributed TE HVAC Systems

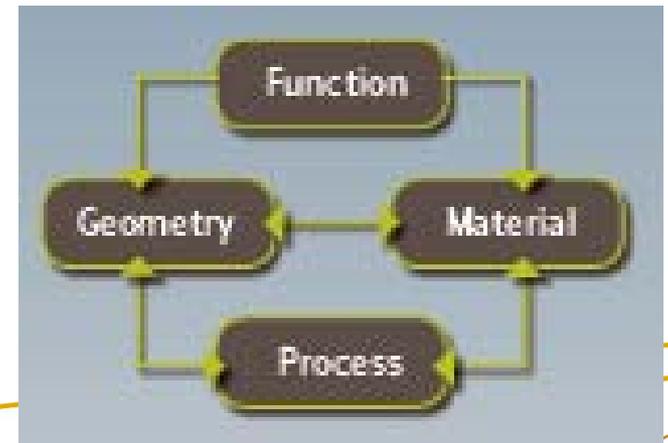
- DOE Project in Advanced TE HVAC Systems for Automobiles
  - Zonal Climate Control for Thermal Comfort
  - Compact Microtechnology Heat Exchangers
    - Reduce Weight & Volume
    - Low Cost Manufacturing
  - Coupled with Compact TE HVAC Systems
  - Wicking Systems for Water Management
    - Leveraging Nano-Scale Coating Technology
  - Significant Microtechnology Cost Modeling
    - Cost Sensitivities Identified
    - Low-Cost Manufacturing Avenues Being Developed
    - Sensitivities to Production Volumes
    - Material and Process Cost Drivers



Hybrid / PHEV Vehicles



Nano-Scale Coatings

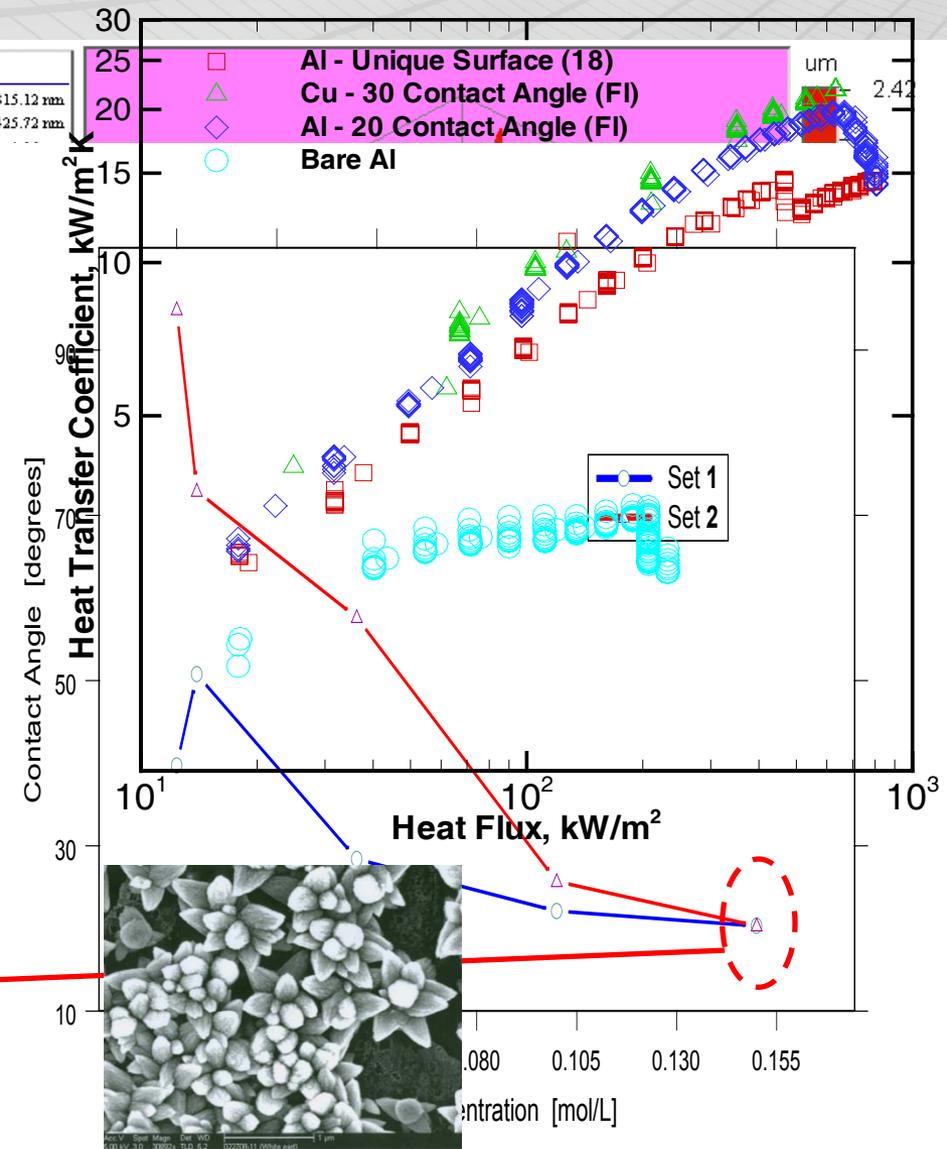
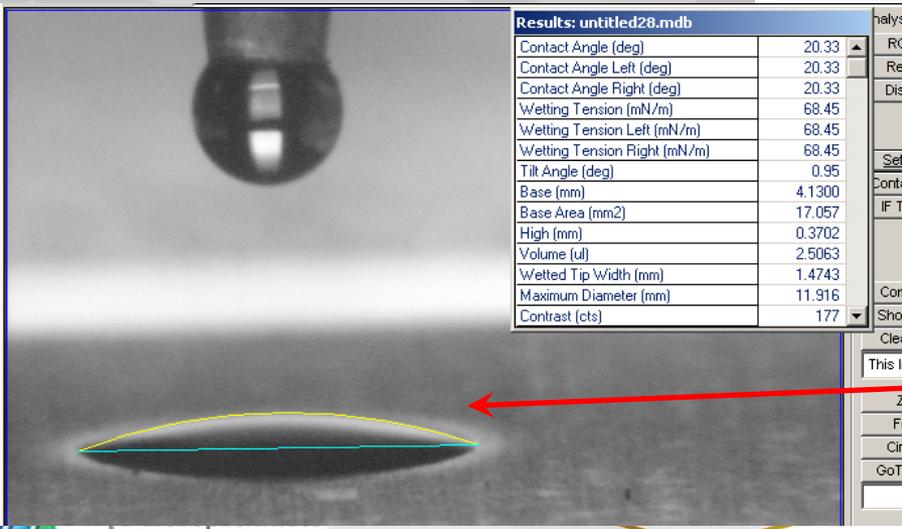


Cost Modeling Approach

# PNNL Nano-Scale Coatings Impact Surface Hydrophobicity and Surface Boiling Heat Transfer

- ZnO on Al Substrate
- $R_{ave} = 315 \text{ nm}$
- $\theta = 20.3^\circ$
- Can Make Super-Hydrophilic Surfaces  $\theta = 0^\circ$
- Bare Aluminum Substrate  $\theta = 104^\circ$
- Huge Ramifications on Water Management / Transport

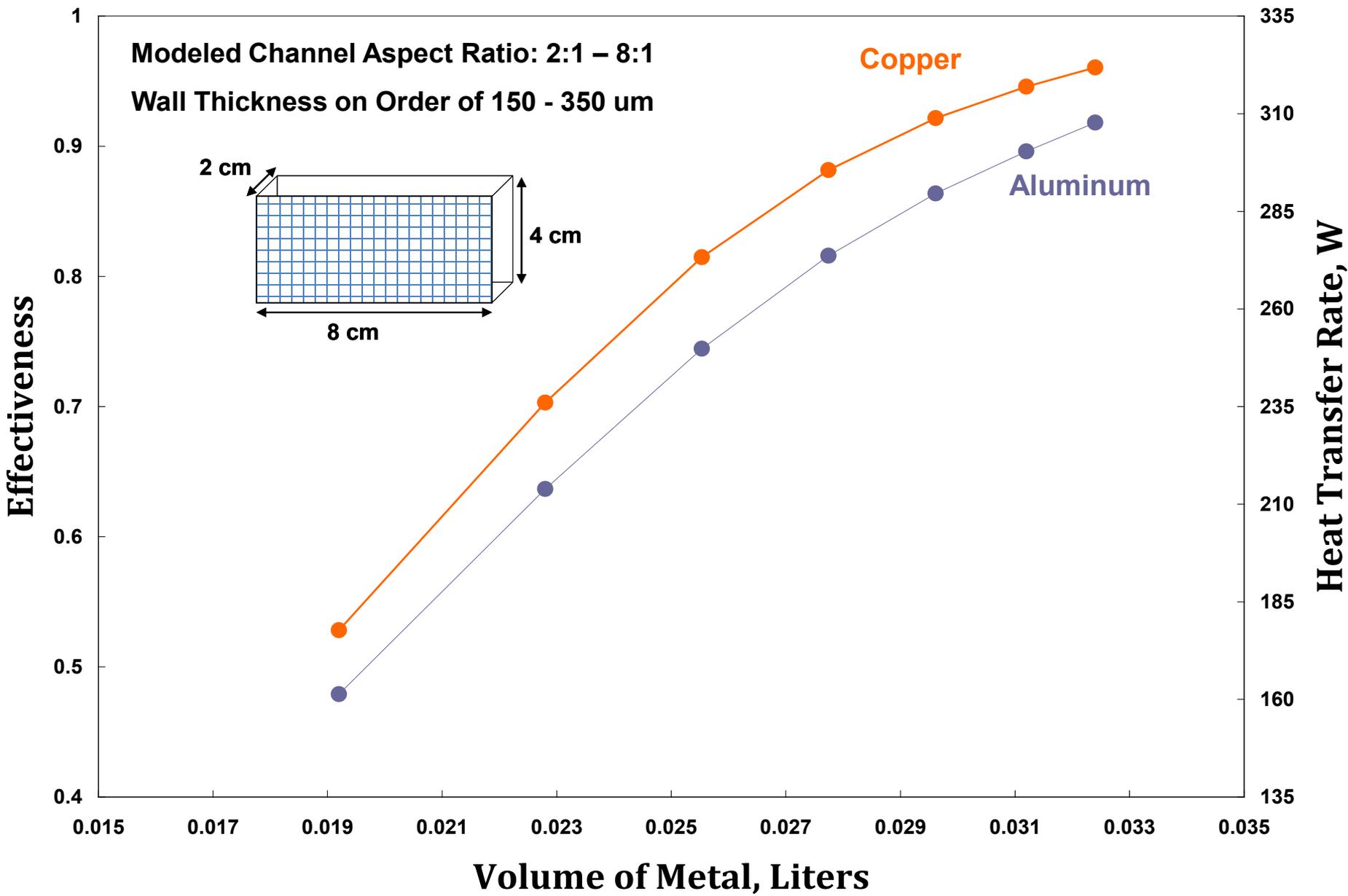
Roughness	
Ra	315.12 nm
Rq	425.72 nm
Rt	.....
Rz	.....
File: WYKA002	
Array Size: 197	
Spacing: 1.99 um	
Terms Removed:	
Tilt	
Filtering:	
None	



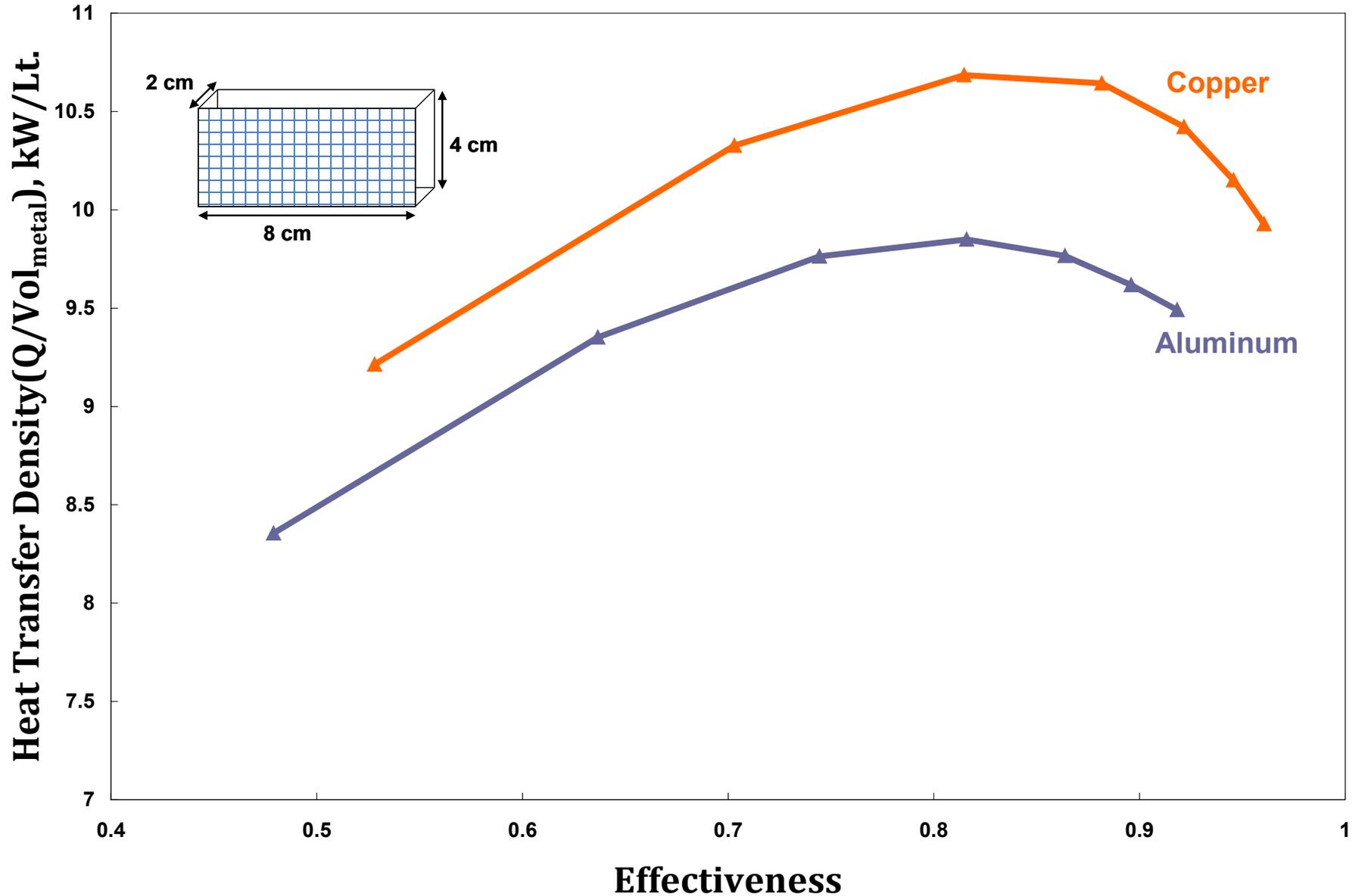
# PNNL Developing High-Performance Microtechnology Heat Transfer Technologies

- TE Cooling / Heating
  - Automotive Distributed HVAC Systems
  - A Number of Microtechnology Designs Are Being Investigated
  - An Example of One Such Design Is Presented Here
- Heat Transfer vs. Pressure Drop Characteristics Quantified

# Effect of Channel Aspect Ratio on Effectiveness



# Effect of Channel Aspect Ratio on Flux Density



# Process-Based Microtechnology Cost Modeling

- Microtechnology Manufacturing Cost is Key to Automotive Applications
- Process-Based Cost Modeling
  - Cost Sensitivities Identified
  - Low-Cost Manufacturing Avenues Being Developed
  - Sensitivities to Production Volumes
  - Material and Process Cost Drivers
- System Performance Modeling Integrated with Cost Modeling to Identify Low-Cost, Manufacturable Microtechnology Designs
- Cost Modeling Incorporates Critical Process & Cost Elements
- Prioritizes R&D Investment Plans & Enables Business Decisions
- Compared 3 Process Approaches for Microtechnology Heat Exchanger Design Discussed Above
  - Cost Modeling for High-Temperature Exhaust Recovery Applications
  - Cost Modeling for Low-Temperature Advanced Cooling Applications

# Process Based Cost Modeling

Bottom-Up Approach to Estimating Cost of Goods Sold (COGS)

Based on Operation of Virtual Manufacturing Line – Breaks Down Cost by Unit Process

## Model Inputs

### Process Flow

Unit Process 1  
Unit Process 2  
Unit Process 3  
Etc.

### Cost Elements

Capital Equipment  
Labor  
Materials  
Energy  
Facilities  
Maintenance



Process-Based Cost  
Model Algorithm

## Model Outputs

### Cost of Goods Sold (COGS)

#### Fixed Costs

Capital Equipment  
Maintenance  
Facilities/Buildings

#### Variable Costs

Direct Labor  
Direct Materials  
Indirect Materials  
Utilities

Process COGS vs. Volume and Pareto

Cost Sensitivity

ID Cost Drivers

Process to Process Comparisons

Define Fabrication Toolbox

Inform R&D Agenda

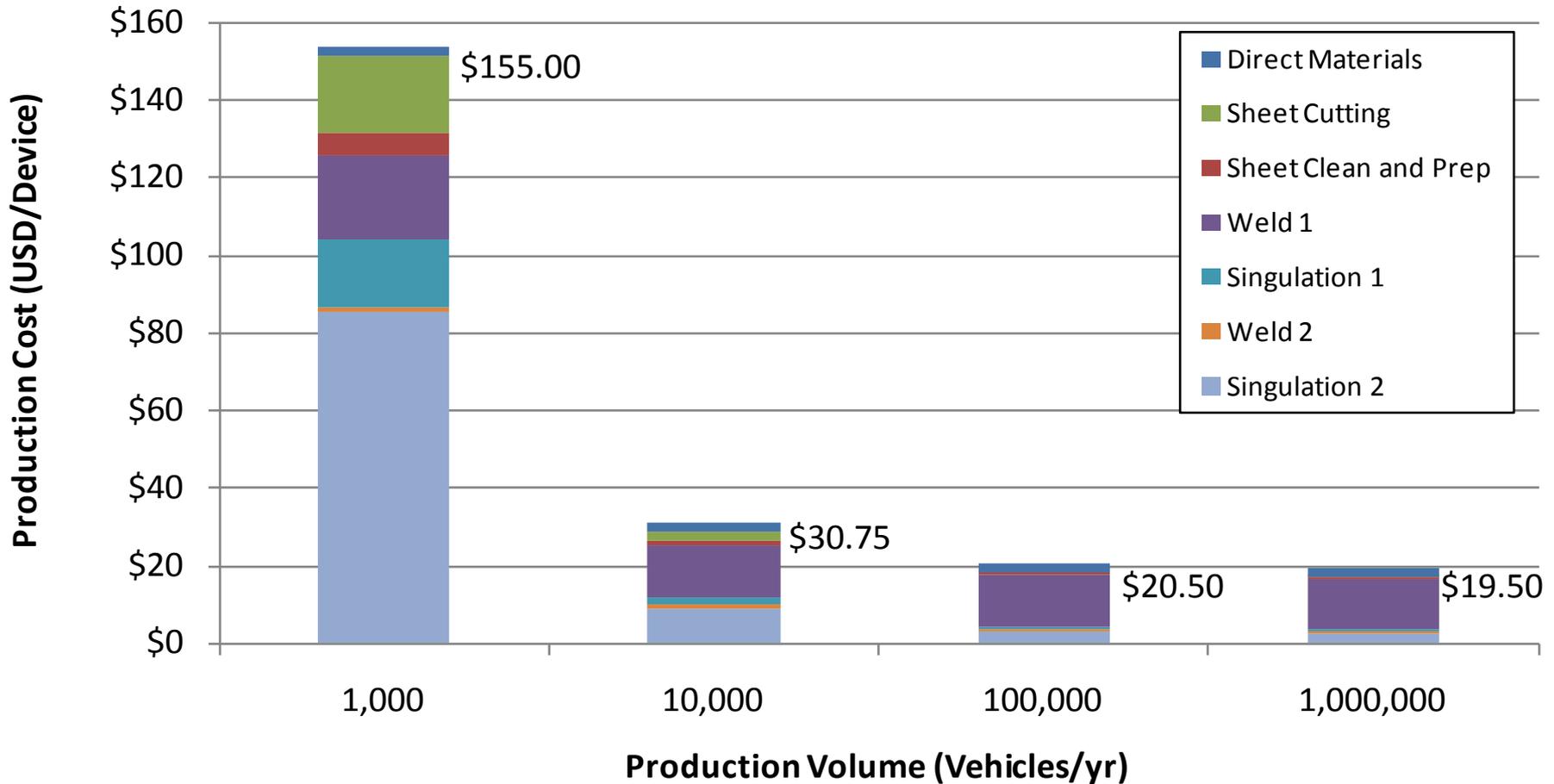
#### Not Included

Overhead & Profit  
Insurance  
Taxes  
Inventory Management  
Accounting  
Marketing  
Sales

Start with Process Flow and Associated Equipment Set

# Integrated HTX COGS Estimation and Pareto : Process "A"

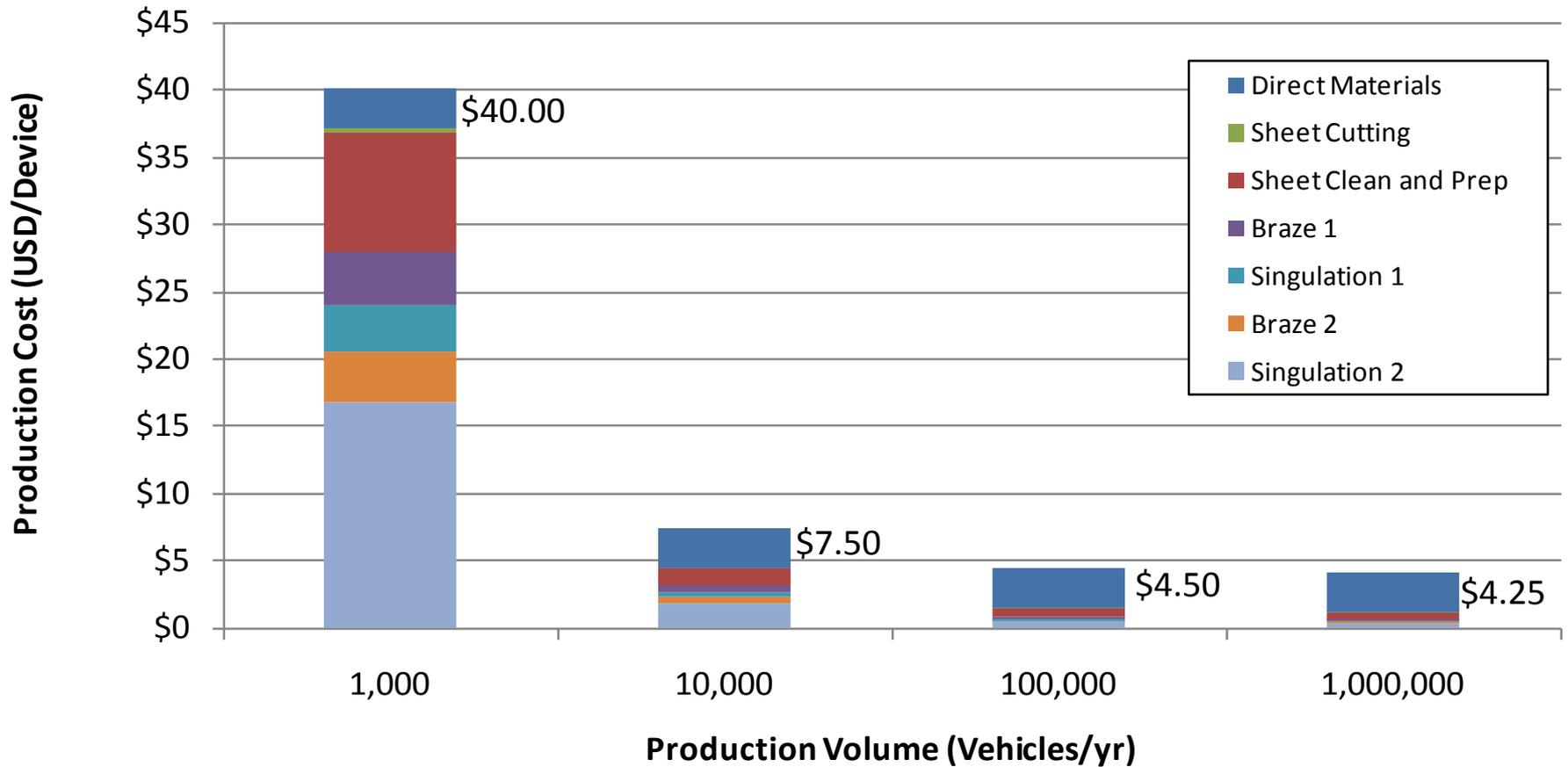
8 HTX per Vehicle / Aluminum HTX / 2 cm x 4 cm x 8 cm HTX Dimensions



Process Relies on Significant Laser Use → Not a Good Design + Process Match Existing, Scalable Fabrication Processes and OTS Production Equipment

# Integrated HTX COGS Estimation and Pareto : Process "B"

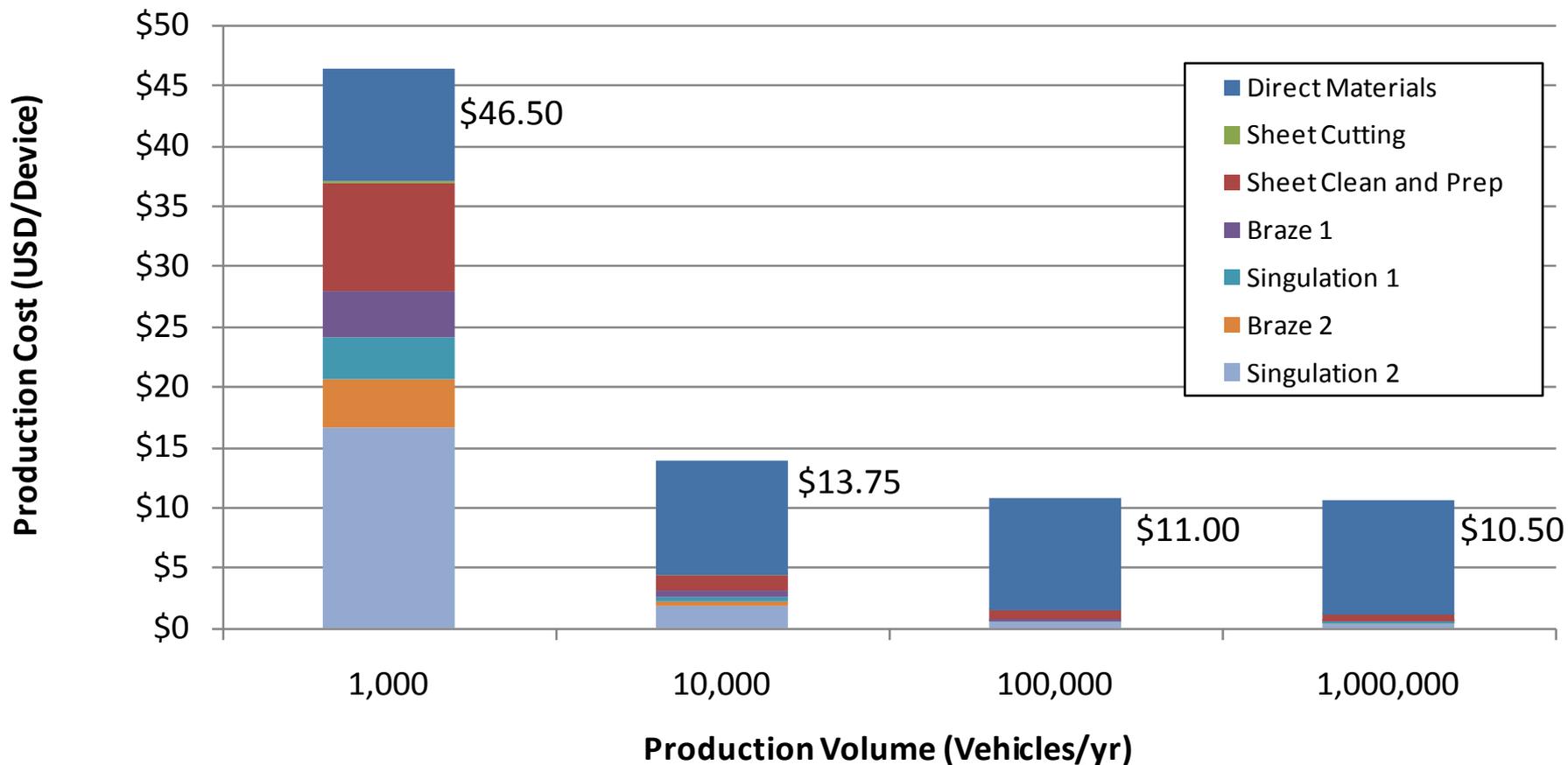
8 HTX per Vehicle / Aluminum HTX / 2 cm x 4 cm x 8 cm HTX Dimensions



Direct Materials Primary Cost Driver at Production Volumes Existing, Scalable Fabrication Processes and OTS Production Equipment

# Integrated HTX COGS Estimation and Pareto : Process "C"

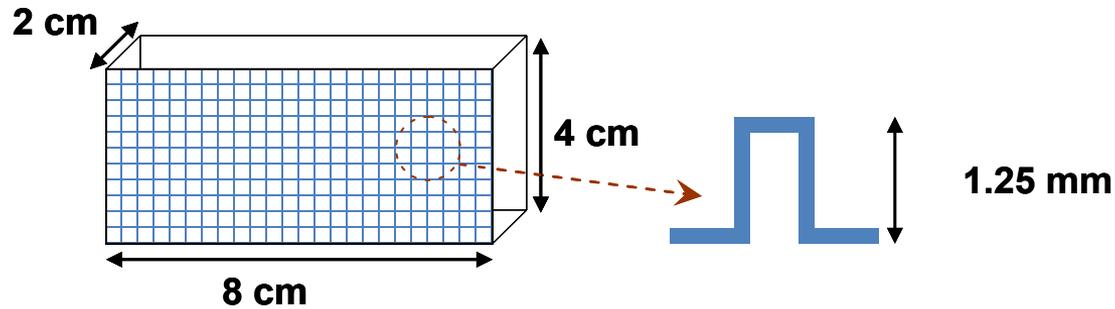
8 HTX per Vehicle / Copper HTX / 2 cm x 4 cm x 8 cm HTX Dimensions



Direct Materials Cost for Copper is 4x that for Aluminum → Drives Cost Improved Yield and Cycle Times in Copper Braze vs. Aluminum Braze

# Summary - Process Comparisons

Annual Volume		Aluminum				Copper	
		Process A		Process B		Process C	
Vehicles	HTX Units	\$/Unit	Capital Equipment (\$k)	\$/Unit	Capital Equipment (\$k)	\$/Unit	Capital Equipment (\$k)
1,000	8,000	\$153.90	\$1,705	\$40.09	\$1,400	\$46.48	\$1,400
10,000	80,000	\$30.85	\$5,455	\$7.44	\$1,400	\$13.87	\$1,400
100,000	800,000	\$20.54	\$43,830	\$4.55	\$2,550	\$10.91	\$2,050
1,000,000	8,000,000	\$19.55	\$459,300	\$4.19	\$17,750	\$10.61	\$14,750



# Summary

- Microtechnology Thermal Systems Required to Enable Compact, Light weight TE Systems
  - TE Power Generation
  - TE Cooling / Heating
- Microtechnology Thermal Systems Successfully Integrating into TE Systems
- Process-Based Cost Modeling is Critical to Developing Low Cost Manufacturing Pathways, Processes, and Materials
  - Cost Modeling Incorporates Critical Process & Cost Elements
  - Cost Sensitivities Identified
  - Low-Cost Manufacturing Avenues Being Developed
  - Sensitivities to Production Volumes
  - Material and Process Cost Drivers Identified
- System Performance Modeling Integrated with Cost Modeling to Identify Low-Cost, Manufacturable Microtechnology Designs
- Prioritizes R&D Investment Plans & Enables Business Decisions

*Thank you for your time and interest*

We are What We Repeatedly do. Excellence, Then, is not an Act, But a Habit.

Aristotle

## Questions & Discussion

